

## IC DESIGN SPECIFICATION

### 1.3-V microPower™ DSP/μC VOICE BAND AUDIO CODEC

Check for Samples: [AIC111](#)

#### FEATURES

- Single Channel Codec
- Noise Shaped Delta Sigma ADC and DAC Technology
- Low Supply Voltage and Current:
  - 1.3-V Typical Power Supply
  - 350-μA Typical Supply Current Drain
- Power Supply Up Monitor and Low Battery Monitor That Also Automatically Shuts Off H-Bridge Output When Battery Decays Below 1.05 V in a Nontransient Manner
- Typical 2.4-μVrms Input Referred Noise With 0.01% Total Harmonic Distortion for Front End and 108-dB Dynamic Range
- ADC Has 87-dB Dynamic Range With 73-dB Total Harmonic Distortion 100 Hz-10 kHz, 40-kHz Sampling Rate
- Typical 55-dB PSRR 100 Hz to 10 kHz for Analog Front End
- Low Noise Programmable Gain Amplifier/Compressor Front End With Programmable Fast and Slow Attack and Decay Rates With Dual or Single Attack and Decay Rate Option
- Typical Output Noise of 12 μVrms With 0.05% Total Harmonic Distortion for Delta Sigma DAC and H-Bridge Output Driver
- Low Jitter Oscillator That Generates all Internal Clocks and Generates 5-MHz Output DSP/μC Clock
- Regulated Bandgap Voltage Reference
- Programmable Functionality via Digital Serial Interface
  - McBSP Interface, DSP Protocol
  - TI TMS320VC54x™, TMS320VC55x™ DSPs
  - SPI Interface, Microcontroller Protocol
  - TI MSP430xx
- External Chip Power Down and Reset
- Available in:

- - 32-Pin QFN 5x5-mm Plastic Package
- - 32-Pad Bumped Die in Waffle Pack (wafer scale packaging)

#### APPLICATIONS

- Hearing Instruments
- Personal Medical Devices
- Hearing Protection
- Aural Processing
- Low-Power Headsets

#### DESCRIPTION

The AIC111 IC design specification serves to provide product development teams with a guideline for how the AIC111 IC is specified and programmable options that are available. The document outlines a top-level block description of the IC along with system specifications and functions. Individual block descriptions and target specifications are also outlined.

The Texas Instruments AIC111 is a TI μPower DSP compatible, or microcontroller compatible audio codec product, or analog interface circuit. The AIC111 is part of a comprehensive family of DSP/μC based high-performance analog interface solutions. The AIC111 is targeted primarily at personal medical devices, such as hearing instruments, aural preprocessing applications, and low-power headset applications. The AIC111 is used in any design requiring a programmable time constant PGA/compressor interface, high dynamic range analog-to-digital converter, an external DSP/μC handling signal processing, or a low distortion digital-to-analog converter with a balanced H-Bridge speaker driver. It supports a CMOS digital interface tailored for TI DSPs with the McBSP protocol such as TMS320VC54x™ DSP family and SPI-based controllers such as TI MSP430x family of microcontrollers. The AIC111 also has an external microphone or sensor supply and bias and power supply up low-battery monitor indicator.



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These devices have limited built-in ESD protection. The leads should be shorted together or the device placed in conductive foam during storage or handling to prevent electrostatic damage to the MOS gates.



This integrated circuit can be damaged by ESD. Texas Instruments recommends that all integrated circuits be handled with appropriate precautions. Failure to observe proper handling and installation procedures can cause damage.

ESD damage can range from subtle performance degradation to complete device failure. Precision integrated circuits may be more susceptible to damage because very small parametric changes could cause the device not to meet its published specifications.

The AIC111 comes in a 32-pin QFN 5x5-mm package. A 32-pad solder ball bumped flip chip die that comes in waffle packs or tape and reel is in preview and will be available 3rd quarter 2003.

### AVAILABLE OPTIONS<sup>(1)</sup>

| Part Number | Package  |
|-------------|--|
| AIC111RHB   | 32-pin QFN (5 mm x 5 mm), in tube.                                       |
| AIC111RHBR  | 32-pin QFN (5 mm x 5 mm), tape and reel                                  |
| AIC111YE    | 32-pad waffle scale chip package, bumped die in waffle pack (commercial) |
| AIC111YE    | 32-pad waffle scale chip package, bumped die in waffle pack (industrial) |
| AIC111YER   | 32-pad (WSCP) bumped die in tape and reel                                |

(1) For the most current package and ordering information, see the Package Option Addendum at the end of this document, or see the TI website at [www.ti.com](http://www.ti.com).

### ABSOLUTE MAXIMUM RATINGS

over operating free-air temperature range unless otherwise noted<sup>(1)(2)</sup>

|                  |                                       |                             | UNIT            |
|------------------|---------------------------------------|-----------------------------|-----------------|
|                  | Input voltage                         | AI or DI pins               | -0.3 V to 4 V   |
|                  | Power supply                          | VDD, power pins             | -0.3 V to 4.5 V |
|                  | Latch-up tolerance                    | JEDEC latch-up (EIA/JEDS78) | 100 mA          |
| T <sub>A</sub>   | Operating free-air temperature range, | Commerical                  | 0°C to 70°C     |
|                  |                                       | Industrial                  | -40°C to 85°C   |
|                  | Functional temperature range          |                             | -15°C to 85°C   |
|                  | Reflow temperature range (flip chip)  |                             | 220°C to 230°C  |
| T <sub>stg</sub> | Storage temperature range             |                             | -40°C to 125°C  |
|                  | Storage humidity                      |                             | 65% R.H.        |

- (1) Stresses beyond those listed under *absolute maximum ratings* may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under *recommended operating conditions* is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
- (2) Specifications are assured operating at maximum device limits for QFN package only, unless otherwise specified.

### ELECTRICAL CHARACTERISTICS

| INPUT/OUTPUT, OPERATING TEMPERATURE AT 25°C |  |                                     |     |              |     |      |
|---|--|-------------------------------------|-----|--------------|-----|------|
|   | PARAMETER  | TEST CONDITION                      | MIN | TYP          | MAX | UNIT |
|   | Digital interface (see <sup>(1)</sup> and <sup>(2)</sup> ) | BUF_DVDD (see Note <sup>(1)</sup> ) |     |              | 3.6 | V    |
| V <sub>IH</sub>                             | High-level input voltage                                   |                                     |     | BUF_DVDD-0.2 |     | V    |
| V <sub>IL</sub>                             | Low-level input voltage                                    |                                     |     | BUF_DVSS+0.2 |     | V    |
| V <sub>OH</sub>                             | High-level output voltage                                  |                                     |     | BUF_DVDD     |     | V    |
| V <sub>OL</sub>                             | Low-level output voltage                                   |                                     |     | BUF_DVSS     |     | V    |
|   | Maximum allowed input voltage (AVIN)                       | Differential                        |     |              | 450 | mVpk |

- (1) DVDD, VDD\_OSC, and AVDD should be within 50 mV, preferably connected together. AVSS1, 2, DVSS, and VSS\_OSC should be within 50 mV, preferably connected together.
- (2) Maximum (0.9 V, DVDD -0.5 V) ≤ BUF\_DVDD ≤ 3.6 V

**ELECTRICAL CHARACTERISTICS (continued)**

| INPUT/OUTPUT, OPERATING TEMPERATURE AT 25°C |  |  |            |            |      |                 |
|---|--|--|------------|------------|------|-----------------|
|   | PARAMETER                                    | TEST CONDITION                             | MIN        | TYP        | MAX  | UNIT            |
|   | Input impedance (AVIN) (see <sup>(3)</sup> ) | Nominal gain = 50x                         |            | 20         |      | kΩ              |
|   | Input capacitance (AVIN)                     |  |            | 5          |      | pF              |
|   | Microphone bias voltage (MIC_VSUP)           | 20-μA maximum                              | 0.87       | 0.94       | 0.99 | V               |
|   | Microphone bias resistor (MIC_BIAS)          |  | 27         | 29.1       | 31   | kΩ              |
|   | H-bridge amplifier output                    | DAC full scale output differential         | Fixed Q    | 3/4 HB_VDD |      | V <sub>PP</sub> |
|   |  |  | Adaptive Q | HB_VDD     |      |                 |
|   | Output resistance                            | Differential, HB - V <sub>DD</sub> = 1.3 V | 20 or 40   |            |      | Ω               |

(3) Driving single-ended:  $R_{in} = R \times [(1+A)/(2+A)]$ , A = PGAC Gain (linear), R = 20.4 kΩ for A ≥ 4 or 20.4 kΩ × (4/A) for A < 4.  $R_{in}(\min) = 17 \text{ k}\Omega$  (A=4),  $R_{in}(\max) = 59.89 \text{ k}\Omega$  (A = 0.89),  $R_{in}(\text{nom}) = 20 \text{ k}\Omega$  (A = 50).

### TERMINAL ASSIGNMENTS

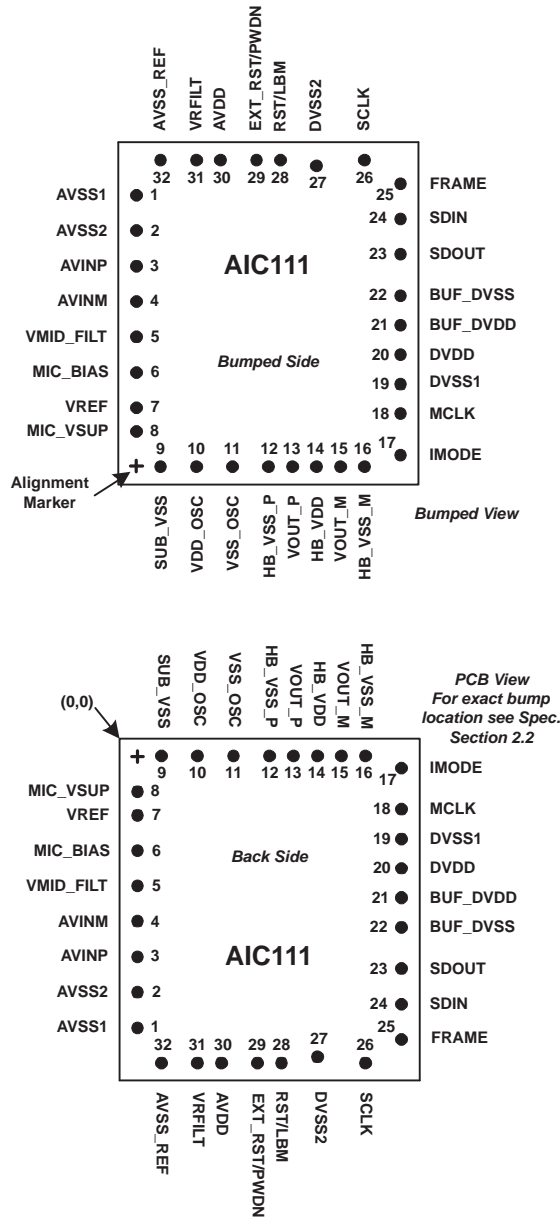


Figure 1. AIC111YE Bumped View and PCB Flipped Pin Placements

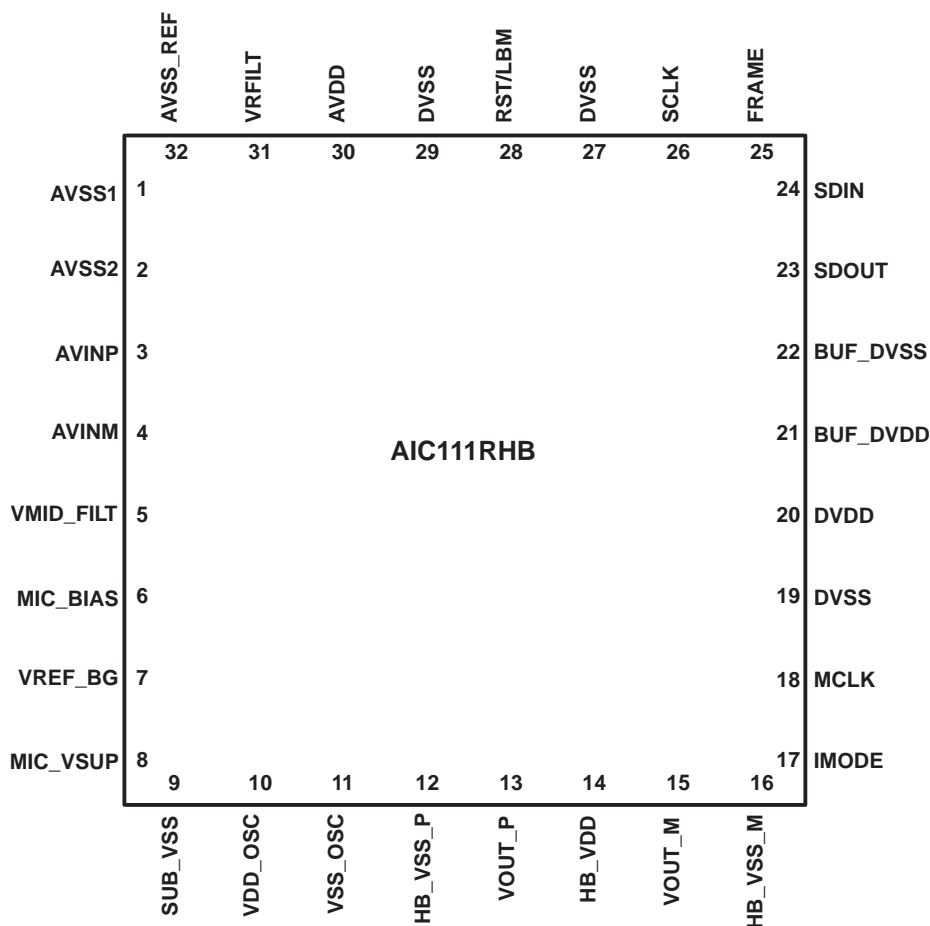


Figure 2. AIC111RHB 32-Pin QFN Pinout

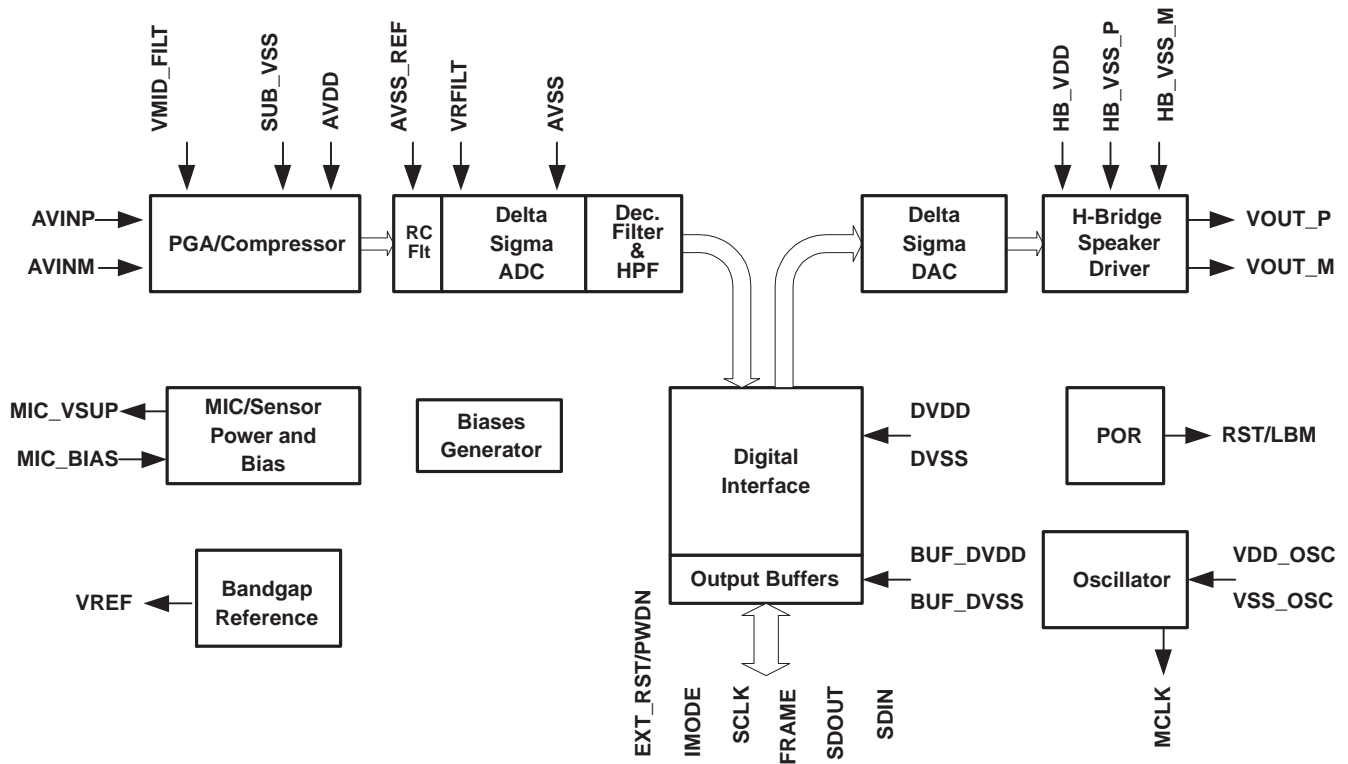
Terminal Functions

| TERMINAL |           |      |   |
|----------|-----------|------|---|
| NO.      | Name      | Type | Description   |
| 1        | AVSS1     | GND  | Ground return for ADC analog circuits   |
| 2        | AVSS2     | GND  | Ground return for PGAC and MIC power analog circuits  |
| 3        | AVINP     | AI   | Noninverting differential analog input coupled through an external 1- $\mu$ F capacitor to external microphone output |
| 4        | AVINM     | AI   | Inverting differential analog signal input coupled through an external 1- $\mu$ F capacitor to ground                 |
| 5        | VMID_FILT | AO   | Midsupply ac ground reference filter pin bypassed by a 1- $\mu$ F capacitor connected to ground                       |
| 6        | MIC_BIAS  | AO   | Source connection of external microphone source follower preamp. (Provides 29.1 k $\Omega$ to AVSS2)                  |
| 7        | VREF      | AO   | Bandgap reference output bypassed by external 1- $\mu$ F VREF filter capacitor  |
| 8        | MIC_VSUP  | AO   | Supply voltage for external microphone source follower preamp bypassed with an external 0.1- $\mu$ F capacitor        |
| 9        | SUB_VSS   | GND  | Isolated substrate VSS for analog circuits  |
| 10       | VDD_OSC   | VDD  | Power pin for internal oscillator   |
| 11       | VSS_OSC   | GND  | Ground return for internal oscillator   |
| 12       | HB_VSS_P  | GND  | Ground return for noninverting stack of H-bridge amplifier  |
| 13       | VOUT_P    | AO   | Noninverting H-bridge output voltage  |
| 14       | HB_VDD    | VDD  | Power pin for H-bridge amplifier  |
| 15       | VOUT_M    | AO   | Inverting H-bridge output voltage   |

### Terminal Functions (continued)

| TERMINAL NO. | Name         | Type | Description   |
|--------------|--------------|------|---|
| 16           | HB_VSS_M     | GND  | Ground return for inverting stack of H-bridge amplifier                                 |
| 17           | IMODE        | DI   | Digital interface format selection pin  |
| 18           | MCLK         | DO   | 5-MHz output clock for external DSP/μC  |
| 19           | DVSS1        | GND  | Ground return for digital circuits  |
| 20           | DVDD         | VDD  | Power pin for digital circuits  |
| 21           | BUF_DVDD     | VDD  | Power pin for interface digital I/O circuits  |
| 22           | BUF_DVSS     | GND  | Ground return for interface digital I/O circuits  |
| 23           | SDOUT        | DO   | Digital interface serial data output pin  |
| 24           | SDIN         | DI   | Digital interface serial data input pin   |
| 25           | FRAME        | DO   | Digital interface serial data framer  |
| 26           | SCLK         | DO   | Digital interface serial shift clock  |
| 27           | DVSS2        | GND  | Ground return for digital circuits  |
| 28           | RST/LBM      | DO   | Provides external reset and low battery monitor   |
| 29           | EXT_RST/PWDN | DI   | Powers down all analog blocks and holds digital outputs low until internal system is up |
| 30           | AVDD         | VDD  | VDD power pin for analog circuits   |
| 31           | VRFILF       | AO   | Positive ADC reference pin bypassed with 1-μF capacitor to AVSS_REF                     |
| 32           | AVSS_REF     | GND  | Ground for ADC voltage reference  |

Figure 3. FUNCTIONAL BLOCK DIAGRAM



## OPERATION

The power source may be a zinc-air battery operating at a typical voltage of 1.3 V. A single external de-coupling capacitor of 1 μF is recommended on the main power supply.

| VOLTAGE and CURRENT, OPERATING TEMPERATURE AT 25°C        |  |     |     |     |      |
|---|--|-----|-----|-----|------|
| PARAMETER   | TEST CONDITION   | MIN | TYP | MAX | UNIT |
| AVDD, DVDD (All pins of type AVDD, DVDD in pin-out table) | Steady-state battery supply  | 1.1 | 1.3 | 1.5 | V    |
| I <sub>S</sub> (supply current)                           | <ul style="list-style-type: none"> <li>Unloaded: H-Bridge output open</li> <li>Microphone resistor model connected (see Figure 5)</li> <li>Power supplies = 1.3 V</li> <li>No receiver attached</li> </ul> |     | 350 |     | μA   |

### FUNCTIONAL INPUT CHANNEL PERFORMANCE REQUIREMENTS

The front end is defined as the differential signal path from the PGA/compressor inputs, AVINP, and AVINM through the delta-sigma ADC and decimation filter.

Typical Conditions; deviations are noted in table.

- Operating Temperature Range: 0°C to 70°C. All specification are at 25°C and 1.3 V unless otherwise noted.
- AVDD, DVDD range: 1.1 V to 1.5 V
- AVINP, AVINM inputs: AC coupled, Frequency ranging from 100 Hz-10 kHz
- Measurement Bandwidth: 100 Hz-10 kHz A-weighted.
- Idle channel definition: AVINP and AVINM are both ac-coupled to AVSS.
- Typical PGAC gain range is -1 dB to 40 dB.
- Maximum input voltage: 450 mVpk.

| PARAMETER        | TEST CONDITION                                   | MIN | TYP  | MAX  | UNIT   |
|------------------|--|-----|------|------|--------|
| Broad-band noise | Input referred idle channel                      |     | 2.4  |      | μV RMS |
| THD (low level)  | AVIN ≤ PGAC threshold (see Note <sup>(1)</sup> ) |     | 0.01 | 0.2% |        |
| DC Offset        | Idle channel                                     | -5  | 0    | 5    | mV     |
| Droop at 10 kHz  | Referenced to amplitude at 1 kHz                 |     | 1.2  |      | dB     |

(1) PGAC threshold = PGAC threshold voltage/maximum gain of PGAC.

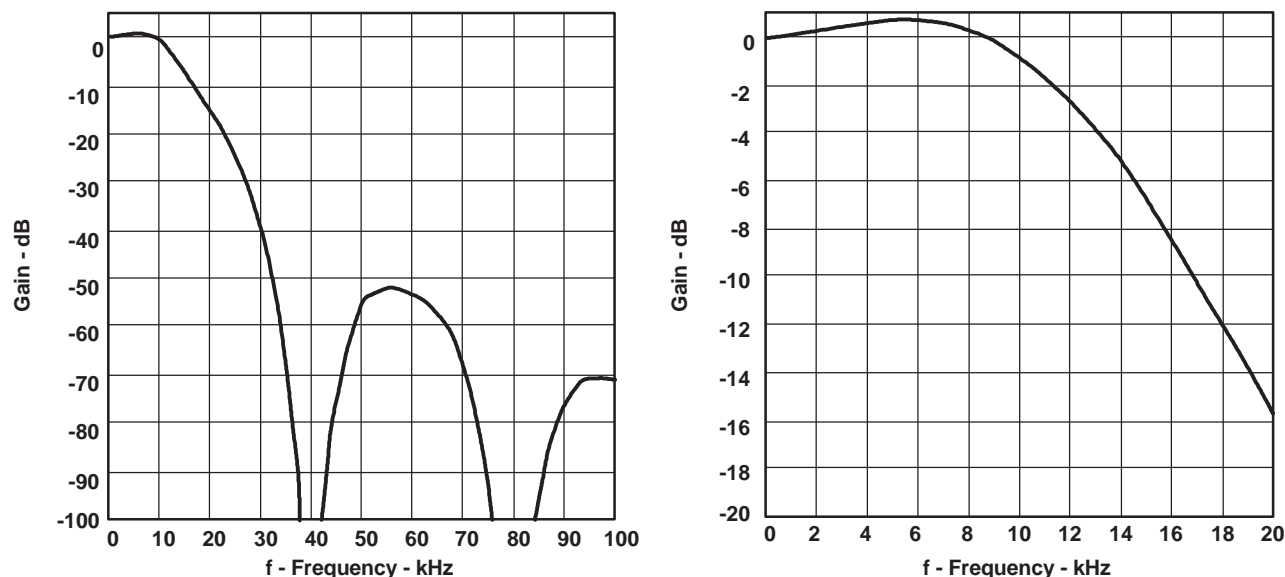


Figure 4. Input Channel Frequency Response With HPF Bypassed

## ANALOG-TO-DIGITAL CONVERTER FILTERED INPUT VOLTAGE REFERENCE

**Function** - Filters analog supply AVDD for DS-ADC reference. With a recommended 0.1- $\mu$ F external capacitor between pins VRFILT and AVSS\_REF, the pole is set at approximately 72 Hz, with 1  $\mu$ F, the pole is set at approximately 7 Hz.

## PROGRAMMABLE GAIN AMPLIFIER AND COMPRESSOR

### **Function:**

The programmable gain amplifier and compressor (PGAC) amplifies the microphone or sensor output signal, provides an appropriate impedance to the microphone buffer or sensor, and provides input gain compression limiting depending on the input signal level if one is not using the fixed gain mode, where the PGAC gain is set by selected register bits. Input compression limiting is discrete automatic gain correction (AGC) based on detecting the peak input signal level using a peak detector circuit that has programmable time responses to provide AGC control, and is intended to prevent a steady state input level up to the defined PGAC limit from being clipped. The attack/release times of the PGAC are programmable by internal clock selection inside the PGAC digital level circuitry that affects the rate of gain changes.

The PGAC has four modes of operation: automatic dual-rate (default), automatic single-rate, fixed single-rate, and fixed immediate. Mode selection is controlled by bits 3 and 2 of the PDCREG register.

### **AUTOMATIC DUAL-RATE MODE (00, DEFAULT):**

In this mode of operation, the PGAC has two attack (gain decrease) rates and two release (gain increase) rates, which may be selected by programming the FASTARREG and FORMAT4 registers. Internally, two counters are used to control the compressor gain. The fast rate counter responds at the fast attack and release rates, and it counts down at the attack rate to decrease the PGAC gain if the output of the PGAC is instantaneously larger than a preset threshold (PGAC\_THRES = 400-mV peak), or it counts up to increase the gain, up to the maximum allowed gain as set by the PGACREG register, if the output of the PGAC falls below a second threshold, which is 3 dB lower (283-mV peak), which provides hysteresis. Before the gain is allowed to increase, the signal at the output of the PGAC must be below the lower threshold for a period of time which is controlled by bit 4 of PDCREG, and can be 50 ms (0, default) or 25 ms (1). The slow-rate counter responds at the slow attack and release rates, and it attempts to track the state of the fast rate counter. The PGAC gain is determined by whichever counter is smaller. In this way, the PGAC can respond and recover rapidly to short signal bursts while responding more slowly to the signal average.

### **AUTOMATIC SINGLE-RATE MODE (01):**

In this mode of operation, the PGAC has one attack rate and one release rate, which may be selected by programming the FASTARREG register. The operation of the PGAC is similar to the dual-rate mode, except that the slow-rate counter is disabled and the PGAC gain is solely determined by the fast-rate counter.

### **FIXED SINGLE-RATE MODE (10):**

In this mode of operation, the PGAC gain tracks the value specified in the PGACREG register regardless of the signal amplitude, and changes in PGACREG cause the gain to decrease or increase at the corresponding fast attack or release rate specified in the FASTARREG register.

### **FIXED IMMEDIATE MODE (11):**

In this mode of operation, the PGAC gain tracks the value specified in the PGACREG register regardless of the signal amplitude, and changes in PGACREG cause the gain to change immediately to the desired gain without stepping through the intermediate gain states.

Bit 7 of the PGACREG register controls the PGAC gain read mode. While this bit is low (default), reading PGACREG returns the contents of PGACREG. However, if this bit is set high, then any subsequent read(s) of PGACREG returns the actual, instantaneous PGAC gain. This information may be useful, for example, for dynamic range expansion, effectively undoing the compression effect in the automatic modes of operation.

## **CHARACTERISTICS**

: Compression limits the PCAG output. PGACREG is a programmable register.



**SPECIFICATIONS AT 25°C, AVDD = 1.3 V<sup>(2)</sup> (3)**

| PARAMETER                      | TEST CONDITIONS | MIN | TYP | MAX | UNIT             |
|--------------------------------|-----------------|-----|-----|-----|------------------|
| <b>Input Signal Parameters</b> |                 |     |     |     |                  |
| Maximum signal swing           | Gain = -1 dB    |     | 900 |     | mV <sub>PP</sub> |
| <b>Block Parameters</b>        |                 |     |     |     |                  |
| Gain size step                 |                 | 0.3 | 0.5 | 0.7 | dB               |

(2) Based on a system clock of 1.280 MHz.

(3) For fixed gain mode the rate is 80 KdB/s to new programmed value of gain. All intermediate 0.5 dB gain steps are passed through to reach new gain.

**DELTA SIGMA A/D CONVERTER/ANTI-ALIAS FILTER**

**Function:** Converts the PGAC differential output to a digital word with an equivalent dynamic range of approximately 14 bits.

**Characteristics:** The delta sigma ADC has a 64 oversampling ratio, a 1.28-MHz master clock, and a 40-kHz output data rate. Digital coding is 2s complement. Tones are at least 12 dB below broadband noise level. Full-scale signal range corresponds to  $+2^{15}$ ,  $-1$ ,  $-2^{15}$

**Table 1. SPECIFICATIONS AT 25°C, AVDD = 1.3 V**

| PARAMETER          | TEST CONDITIONS         | MIN | TYP  | MAX | UNIT |
|--------------------|-------------------------|-----|------|-----|------|
| Block parameters   |                         |     |      |     |      |
| Dynamic range      | -3 dB rel. to reference |     | 87   |     | dB   |
| Input sample rate  |                         |     | 1.28 |     | MHz  |
| Output sample rate |                         |     | 40   |     | kHz  |
| THD                | BW: 100 Hz-10 kHz       |     | 85   |     | dB   |

**DIGITAL HIGH-PASS FILTER**

**Function:** Provide a high-pass filter in ADC signal path. The high-pass filter (HPF first order) removes dc offsets introduced into the channel. FORMAT1 register selections for a 50 Hz, 100 Hz, or bypass are available.

**Characteristics:** Programmable selections for a 50 Hz, 100 Hz, or bypass are available. The default HPF pole is 50 Hz.

**Table 2. SPECIFICATIONS**

| PARAMETER            | TEST CONDITIONS | MIN | TYP | MAX | UNIT |
|----------------------|-----------------|-----|-----|-----|------|
| HPF corner frequency | -3 dB nom mode  |     | 50  |     | Hz   |

**DELTA SIGMA DAC**

**Function:** Generates an over-sampled bit string to drive the H-bridge output amplifier such that when filtered reproduces the desired analog waveform.

**Characteristics:** A 32 times over-sampled modulator multi-bit design.

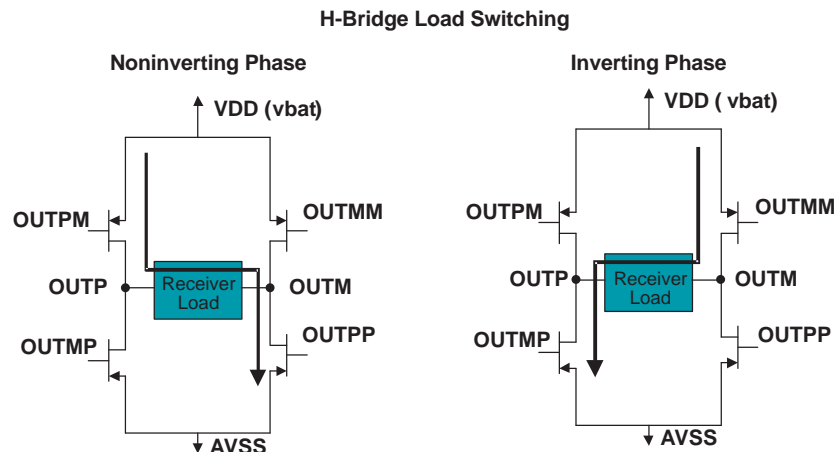
**Table 3. SPECIFICATIONS**

| PARAMETER                   | TEST CONDITIONS     | MIN | TYP | MAX | UNIT |
|-----------------------------|---------------------|-----|-----|-----|------|
| $f_{d(\text{input\_data})}$ | Signal; BW = 10 kHz |     | 40  |     | kHz  |
| $f_{\text{clk}}$            |                     |     | 640 |     | kHz  |

## H-BRIDGE OUTPUT DRIVER

**Function:** An H-bridge output driver efficiently converts the delta sigma DAC modulator output signals. The external load provides the low-pass filtering that recovers the differential analog signal from the H-bridge.

**Characteristics:** Standard H-bridge configuration with transistors sized to differentially drive the load impedance. The load impedance is complex and a function of frequency.



- A. VDD does not necessarily have to be connected to the same potential as AVDD, it could be connected to a higher potential than AVDD, equal to AVDD, but not less than AVDD.

**Figure 5. Definition of Phase and Output Switching Current Polarity**

**Table 4. SPECIFICATIONS AT 25°C, HB\_VDD = 1.3 V**

| PARAMETER               | TEST CONDITIONS   | MIN        | TYP        | MAX | UNIT            |
|-------------------------|---|------------|------------|-----|-----------------|
| <b>Block Parameters</b> |   |            |            |     |                 |
| DC offset               | Idle channel; Differential across VOUT_P and VOUT_M   | -5         | 0          | 5   | mV              |
| Broadband noise         | Idle channel, measured at output of channel, BW = 100 Hz-10 kHz, HB_VDD = 1.3 V, A-weighted | Fixed Q    | 33         |     | $\mu$ Vrms      |
|                         |   | Adaptive Q | 12         |     |                 |
| THD                     | BW = 100 Hz-10 kHz  |            | 0.03%      |     |                 |
| Switching frequency     |   |            | 640        |     | kHz             |
| Maximum output swing    |   | Fixed Q    | 3/4 HB_VDD |     | V <sub>PP</sub> |
|                         |   | Adaptive Q | HB_VDD     |     |                 |

## MICROPHONE POWER SUPPLY

**Function:** The microphone power supply circuit provides a constant power supply voltage and bias current for the microphone preamp or sensor bias, provides a low-noise voltage reference (ac ground) for the PGAC, provides regulated PGAC comparator threshold levels, provides bandgap regulated POR comparator trip voltage levels, and provides a bandgap regulated current for the biases generator circuit.

**Characteristics:** The low-dropout regulator configuration or single stage, single-pole amplifier drives an external 0.1- $\mu$ F capacitor. The regulator does not oscillate under no-load or loaded conditions. The circuit supplies up to 50- $\mu$ A of continuous current.

**Table 5. SPECIFICATIONS AT 25°C, AVDD = 1.3 V**

| PARAMETER | TEST CONDITIONS  | MIN  | TYP  | MAX  | UNIT |
|-----------|--|------|------|------|------|
| MIC_VSUP  | $I_L = 20 \mu$ A   | 0.87 | 0.94 | 0.97 | V    |
| VMID_FILT | $0.59 \times AVDD$                                       |      | 0.78 |      | V    |
| PSRR      | 0.1- $\mu$ F external bypass cap from MIC_VSUP to AVSS2. |      | 55   |      | dB   |

**Table 5. SPECIFICATIONS AT 25°C, AVDD = 1.3 V (continued)**

| PARAMETER        | TEST CONDITIONS | MIN | TYP | MAX | UNIT |
|------------------|-----------------|-----|-----|-----|------|
| Output impedance |                 |     | 1.5 |     | kΩ   |

## MCLK Output

**Function:** Provides a clock signal for external use.

**Table 6. SPECIFICATIONS AT 25°C, VDD\_OSC, DVDD, BUF\_DVDD = 1.3 V**

| PARAMETER  | TEST CONDITIONS | MIN | TYP  | MAX | UNIT |
|------------|-----------------|-----|------|-----|------|
| Frequency  |                 | 4.7 | 5.12 | 5.5 | MHz  |
| Jitter     | RMS jitter      |     | 150  |     | ps   |
| Duty cycle |                 |     | 50%  |     |      |

## POWER-ON RESET

**Function:** Provides a reset signal upon power up (stable voltage reference) that initializes the digital interface. It also provides a gating signal to the delta-sigma DAC modulator to prevent audible *pops* and *clicks* from erroneous data sent to the H-bridge circuit at power up and during periods when battery voltage has degraded below 1.05 V for an extended period of time (typically greater than 44 μs). The reset signal is asynchronous to MCLK. Digital interface does not start operating until after  $t_{(VDD)\_valid}$  has transpired.

POR has to:

- Deal with system's on/off switch bounce lasting 100 ms or less.
- Detect when the power supply AVDD is  $\geq 1.1$  V to enable the H-bridge output.
- Provide kick-start to oscillator.
- Detect when VDD degrades below 1.05 V for a period of time that is nontransient, and gate H-bridge output.

**Table 7. SPECIFICATIONS AT 25°C, AVDD = 1.3 V**

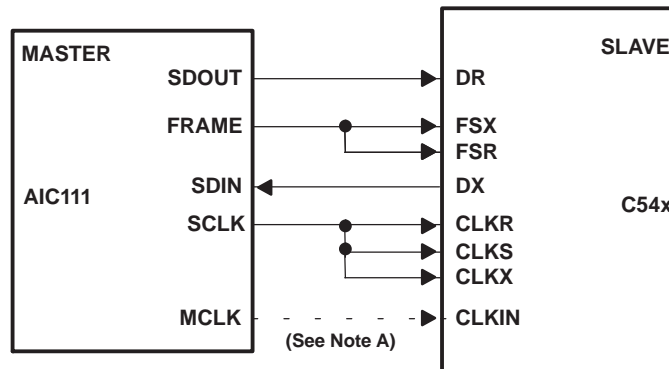
| PARAMETER   | TEST CONDITIONS   | MIN | TYP  | MAX | UNIT |
|---|-------------------|-----|------|-----|------|
| $t_{(VDD)\_valid}$ :<br>Time VDD considered valid at powerup after switch bounce has settled.       | $V_{DD} > 1.1$ V  |     | 100  |     | ms   |
| Allowed transient spike below 1.05 V before H-bridge output and digital interface are not asserted. | $V_{DD} < 1.05$ V |     | 44   |     | μs   |
| POR on  |                   |     | 1.1  |     | V    |
| POR off   |                   |     | 1.05 |     |      |

## DIGITAL INTERFACE

**Function:** The digital interface can be selected (IMODE=LOW) as a serial audio/control interface (SACI), which is the McBSP DSP-codec protocol, or (IMODE=HIGH), a serial peripheral interface (SPI). Either SACI or SPI sends out a 16-bit audio stream from the Δ-S ADC and receives a 20-bit audio stream going to the Δ-S DAC/H-Bridge. Several control functions, READ/WRITE to user registers, are also included totaling five 8-bit registers. Four pins, SCLK, FRAME, SDIN and SDOUT, are employed in SACI or SPI. An internal register map exists that contains read/write program registers for a variety of FORMAT (user) settings. The register bits that are designated *not used* will always read back zero or voltage level VSS regardless of what is written to them.

| DIG INTERFACE PIN | I/O    | DESCRIPTION   |
|-------------------|--------|---|
| SCLK              | Output | Bit shift clock. SCLK has an internal pull down.  |
| FRAME             | Output | Data frame sync: controls the separation of audio channels and provides a reset/synchronization to the interface's internal state machine. FRAME has an internal pull down. |
| SDIN              | Input  | Serial audio/control data input pin.  |
| SDOUT             | Input  | Serial audio/control data output pin.   |
| IMODE             | Input  | Interface protocol selection pin. LOW=SACI, HIGH=SPI.   |

| DIG INTERFACE PIN | I/O    | DESCRIPTION       |
|-------------------|--------|-------------------|
| MCLK              | Output | Clock output pin. |



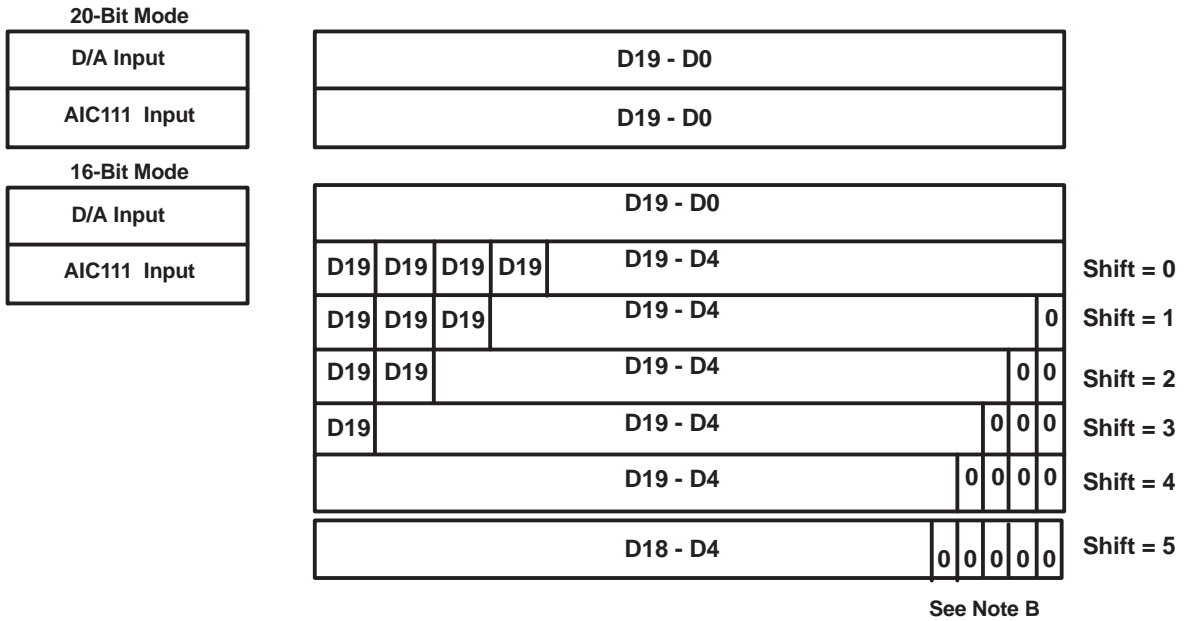
A. The dotted line indicates the connection is not essential for communication to work.

**Figure 6. AIC111 McBSP DSP-Codec Interface**

### McBSP DSP-Codec (SACI) PROTOCOL

Use this protocol when interfacing to TI DSPs.

- The SACI works in a master mode.
- SCLK = 1.28 MHz. FRAME (= 40 kHz) has a 50% duty cycle. FRAME is an output.
- 32-bit control/audio data, written on the SDIN pin, consist of a 20-bit audio word going to the  $\Delta$ - $\Sigma$  DAC, and a 12-bit control word.
- DAC input has two modes of operation, a 20-bit mode, and a 16-bit mode.
- The 12-bit control word consists of: a R/W bit, 3 address bits, and 8-bits of control register content. Note that the R/W bit is defined as 0=READ, and 1=WRITE.
- When the 3 address bits are all zeros, the control function of the SACI is disabled.
- 24-bit audio/control data, read from the SDOUT pin, consist of one 16-bit output from the  $\Delta$ - $\Sigma$  DAC followed by an 8-bit control word.
- All data/control words are formatted as the MSB first.



A. For 5-bit left shift, digital word is limited to 15 bits with saturation.

**Figure 7. AIC111 Data Output**

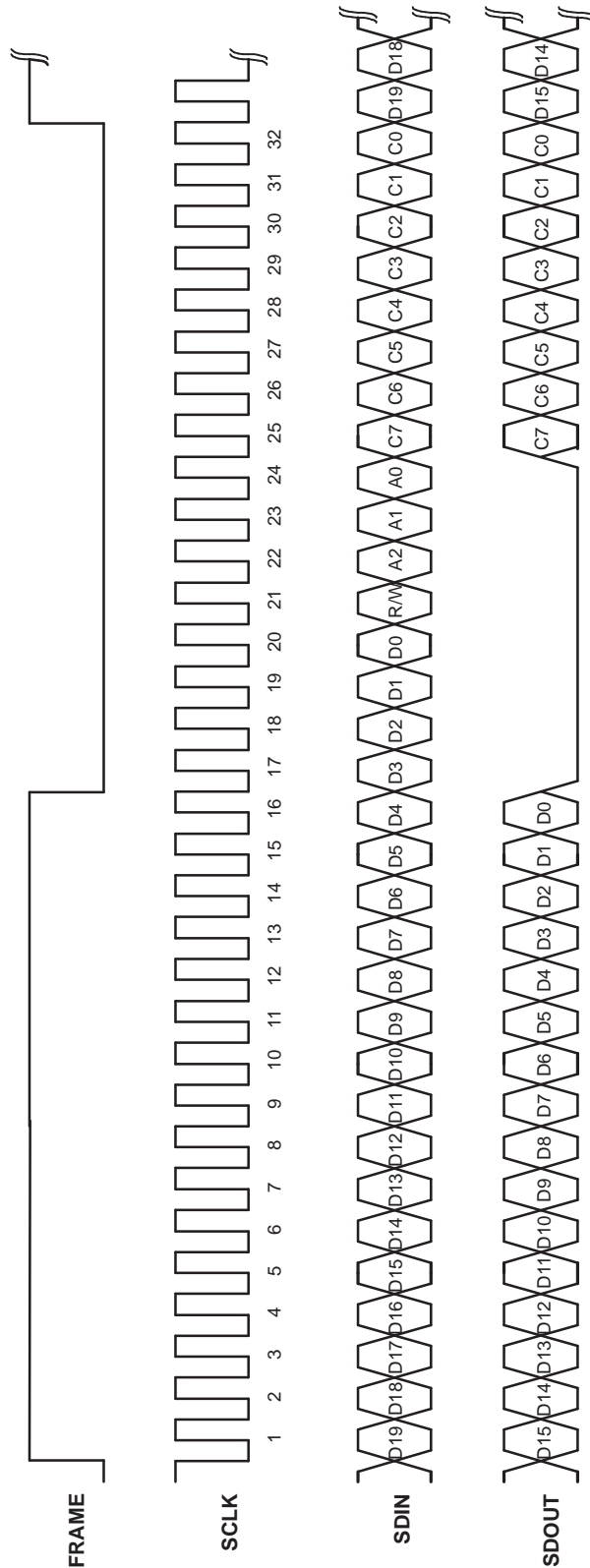


Figure 8. AIC111 DSP-Codec (SACI) Signals (Read = 0, Write = 1)

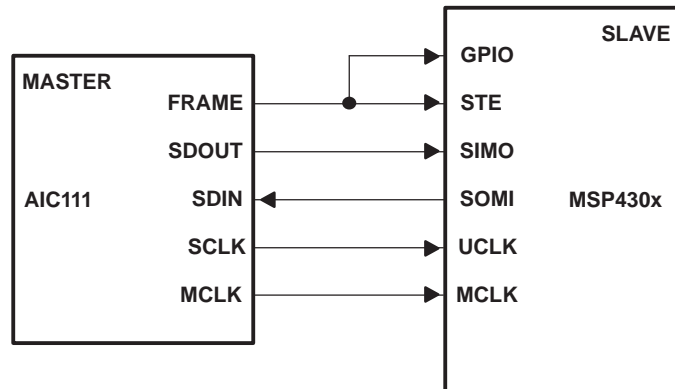
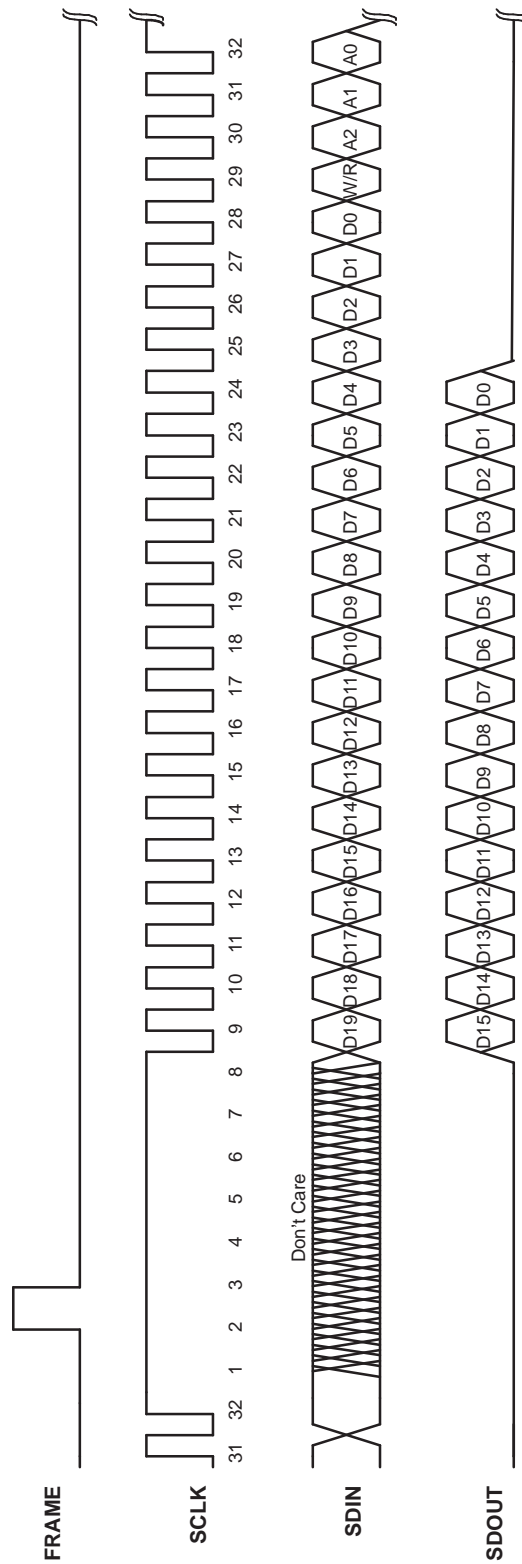


Figure 9. AIC111 SPI I/O Diagram

### SPI PROTOCOL

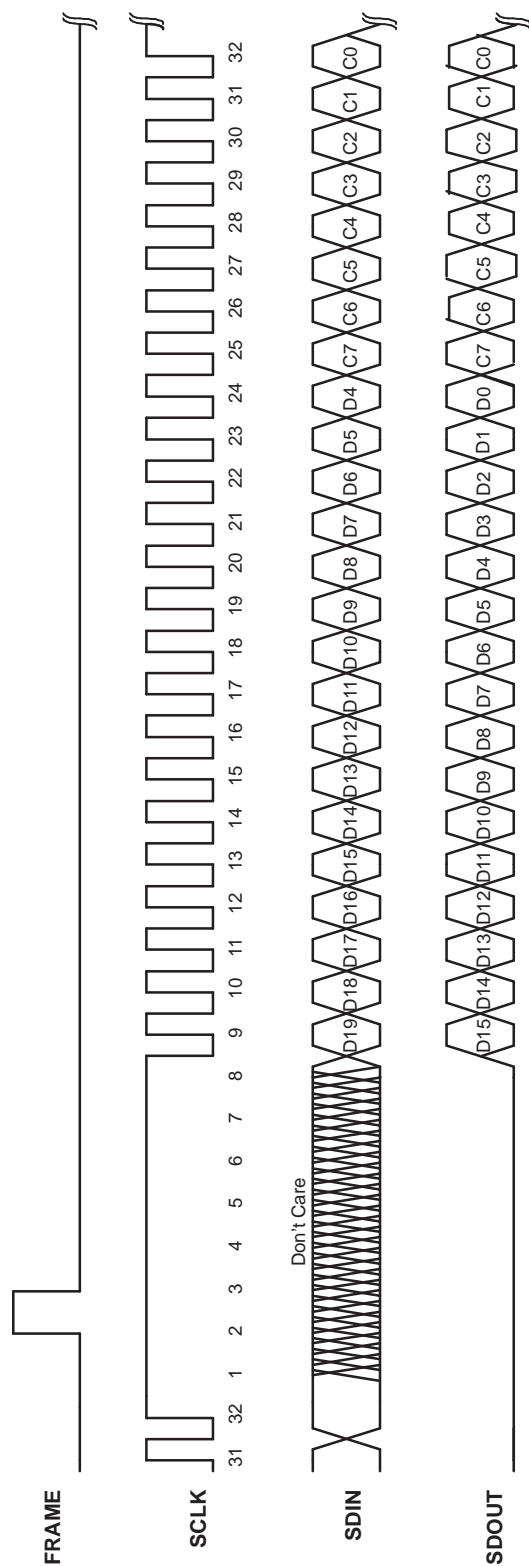
- AIC111 can also implement a master SPI protocol.
- SCLK supplies a bit shift clock of 1.28 MHz to the SPI port of a slave device.
- FRAME must be in the active *low* state prior to data transaction and must stay *low* for the duration of data transaction. Before communication, there are eight silent cycles on SCLK. During this period FRAME also sends a pulse to reset the slave device.
- When the control function is not required, the AIC111 transmits a 16-bit audio word to and receives a 20-bit audio word from the slave device in every FRAME cycle.
- A WRITE/READ of an 8-bit user register (address 0x01 to 0x07) takes two FRAME cycles.
- All data/control words are formatted as the MSB first.



- A. If A2, A1, and A0 = 0, one gets audio data only and W/R is a don't care. If in the previous frame A2, A1, and A0 = 0, then one gets both audio and control data depending on the W/R bit defined as Read = 0 and Write = 1.

**Figure 10. AIC111 SPI Signals**





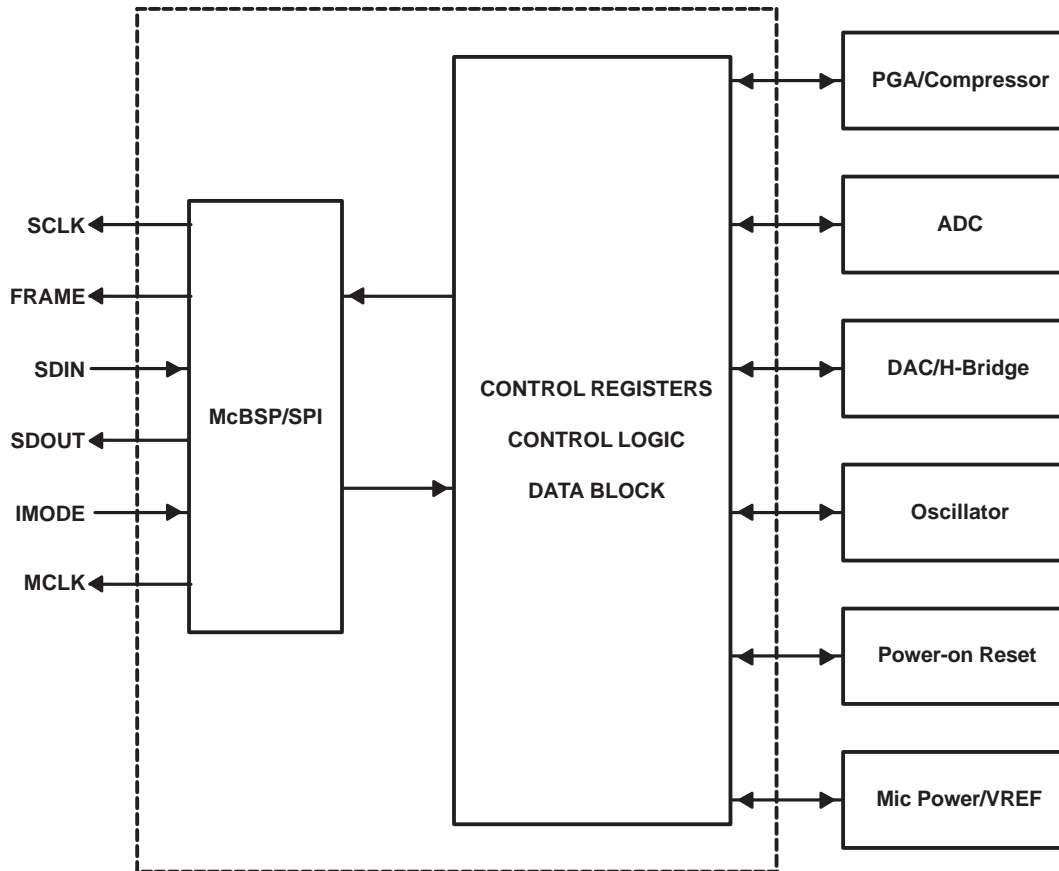
- A. SDIN shows writing to A2, A1, and A0 specified from the previous frame. SDOUT shows reading from A2, A1, and A0 specified from a different previous frame.

Figure 11. AIC111 SPI Signals

**Table 8. DIGITAL INTERFACE TIMING**

| PARAMETER |                 | MIN | TYP       | MAX | UNIT |
|-----------|-----------------|-----|-----------|-----|------|
| F_sclk    | SCLK frequency  |     | 1.28      |     | MHz  |
| F_frame   | FRAME frequency |     | F_sclk/32 |     | MHz  |

**Figure 12. DIGITAL INTERFACE BLOCK DIAGRAM**



**Table 9. REGISTER MAP AND REGISTER BIT DEFINITIONS**

| ADDRESS | REGISTER NAME <sup>(1)</sup> | DETAILED DESCRIPTION                      |
|---------|------------------------------|---|
| 0x00    | Reserved                     | Reserved for future use                   |
| 0x01    | PGACREG                      | PGAC gain register                        |
| 0x02    | HPFSFTREG                    | HPF and shift control register            |
| 0x03    | PDCREG                       | Power-down control register               |
| 0x04    | FASTARREG                    | Fast attack/release rate control register |
| 0x05    | SLOWARREG                    | Slow attack/release rate control register |
| 0x06-07 | Reserved                     | Reserved for future use                   |

(1) Do not write to the reserved registers.

**Table 10. PGACREG**

| BIT | NAME           | FUNCTION   | DEFAULT=0x46 |
|-----|----------------|--|--------------|
| 7   | PGAC_READ_MODE | Select register contents or actual gain to read<br>0: Read FORMAT0 register contents (default)<br>1: Read actual PGAC gain |              |

**Table 10. PGACREG (continued)**

| BIT | NAME            | FUNCTION  | DEFAULT=0x46 |
|-----|-----------------|---|--------------|
| 6:0 | PGAC_GAIN [6:0] | PGAC gain adjustment (0.5 dB steps). A full table is found in the <a href="#">APPENDIX</a> of this data sheet.<br>0x52 = +40.0 dB<br>0x51 = +39.5 dB<br>0x50 = +39.0 dB<br>...<br>0x46 = +34.0 dB (default)<br>....<br>0x01 = -0.5 dB<br>0x00 = -1.0 dB |              |

**Table 11. HPFSFTREG**

| BIT | NAME          | FUNCTION   | DEFAULT=0x11 |
|-----|---------------|--|--------------|
| 7   | DBUFF_EN      | Enable weak (1/2 strength) dig I/O buffer  |              |
| 6:5 | HPF_CTL [1:0] | Control bits for high-pass filter<br>00: normal mode<br>01: HPF bypass<br>10: 100 Hz corner frequency<br>11: Not used  |              |
| 4:2 | SHIFT [2:0]   | Select shift bits when ADC 16-b output is used as DAC 20-b input.<br>000: no shift -24 dB gain<br>001: 1b left shift -18 dB gain<br>010: 2b left shift -12 dB gain<br>011: 3b left shift -6 dB gain<br>100: 4b left shift (default) 0 dB gain<br>101: 5b left shift +6 dB gain<br>11X: 5b left shift |              |
| 1:0 | DAC_MODE      | Select DAC mode of operation.<br>00: DAC off, powered down<br>01: 16-bit input goes through shifter (default)<br>10: 20-bit input bypasses shifter<br>11: ADC"DAC digital loopback   |              |

**Table 12. PDCREG**

| BIT | NAME             | FUNCTION  | DEFAULT=0x00 |
|-----|------------------|---|--------------|
| 7   | DAC_ADAPTIVE_Q   | 0 = fixed quantization, 1 = adaptive quantization   |              |
| 6   | HB_OUT_EN        | H-bridge output enable  |              |
| 5   | HB_DRIVE         | H-bridge drive strength, 0 = 40Ω, 1 = 20 Ω  |              |
| 4   | HIST_TIMEOUT_SEL | PGAC hysteresis timeout select<br>0: 50 ms (default)<br>1: 25 ms  |              |
| 3:2 | PGAC_GAIN_MODE   | Set gain mode of PGAC<br>00: Automatic, dual rate (default)<br>01: Automatic, single rate<br>10: Fixed, single rate<br>11: Fixed, immediate |              |
| 1   | MIC_VSUP_PD      | Power down MIC_VSUP   |              |

**Table 12. PDCREG (continued)**

| BIT | NAME        | FUNCTION            | DEFAULT=0x00 |
|-----|-------------|---------------------|--------------|
| 0   | FRONTEND_PD | Power down PGAC+ADC |              |

**Table 13. FASTARREG PGAC Fast Rates**

| BIT | NAME         | FUNCTION   | DEFAULT=0xF7 |
|-----|--------------|--|--------------|
| 7:4 | ATTACK<7:4>  | 1111: Attack rate = 80000 dB/s<br>1110: Attack rate = 40000 dB/s<br>1101: Attack rate = 20000 dB/s<br>1100: Attack rate = 10000 dB/s<br>1011: Attack rate = 5000 dB/s<br>1010: Attack rate = 2500 dB/s<br>1001: Attack rate = 1250 dB/s<br>1000: Attack rate = 625 dB/s<br>0111: Attack rate = 312.5 dB/s<br>0110: Attack rate = 156.25 dB/s<br>0101: Attack rate = 78.13 dB/s<br>0100: Attack rate = 39.1 dB/s<br>0011: Attack rate = 19.53 dB/s<br>0010: Attack rate = 9.77 dB/s<br>0001: Attack rate = 4.88 dB/s<br>0000: Attack rate = 2.44 dB/s |              |
| 3:0 | RELEASE<3:0> | 1111: Release rate = 80000 dB/s<br>1110: Release rate = 40000 dB/s<br>...<br>0001: Release rate = 4.88 dB/s<br>0000: Release rate = 2.44 dB/s  |              |

**Table 14. SLOWARREG PGAC Slow Rates (Dual Rate Mode Only)**

| BIT | NAME         | FUNCTION  | DEFAULT=0x42u |
|-----|--------------|---|---------------|
| 7:4 | ATTACK<7:4>  | 1111: Attack rate = 80000 dB/s<br>1110: Attack rate = 40000 dB/s<br>...<br>0001: Attack rate = 4.88 dB/s<br>0000: Attack rate = 2.44 dB/s     |               |
| 3:0 | RELEASE<3:0> | 1111: Release rate = 80000 dB/s<br>1110: Release rate = 40000 dB/s<br>...<br>0001: Release rate = 4.88 dB/s<br>0000: Release rate = 2.44 dB/s |               |

**APPENDIX**
**Table 15. PGAC GAIN**

| PGAC GAIN VALUES |                |           |         |           |
|------------------|----------------|-----------|---------|-----------|
|                  | BUS NAME       | HEX VALUE | BINARY  | GAIN (dB) |
| PGAC             | PGAC_GAIN<6:0> | 0x52      | 1010010 | 40        |
|                  |                | 0x51      | 1010001 | 39.5      |
|                  |                | 0x50      | 1010000 | 39        |
|                  |                | 0x4F      | 1001111 | 38.5      |
|                  |                | 0x4E      | 1001110 | 38        |
|                  |                | 0x4D      | 1001101 | 37.5      |
|                  |                | 0x4C      | 1001100 | 37        |
|                  |                | 0x4B      | 1001011 | 36.5      |
|                  |                | 0x4A      | 1001010 | 36        |
|                  |                | 0x49      | 1001001 | 35.5      |
|                  |                | 0x48      | 1001000 | 35        |
|                  |                | 0x47      | 1000111 | 34.5      |
|                  |                | 0x46      | 1000110 | 34        |
|                  |                | 0x45      | 1000101 | 33.5      |
|                  |                | 0x44      | 1000100 | 33        |
|                  |                | 0x43      | 1000011 | 32.5      |
|                  |                | 0x42      | 1000010 | 32        |
|                  |                | 0x41      | 1000001 | 31.5      |
|                  |                | 0x40      | 1000000 | 31        |
|                  |                | 0x3F      | 0111111 | 30.5      |
|                  |                | 0x3E      | 0111110 | 30        |
|                  |                | 0x3D      | 0111101 | 29.5      |
|                  |                | 0x3C      | 0111100 | 29        |
|                  |                | 0x3B      | 0111011 | 28.5      |
| 0x3A             | 0111010        | 28        |         |           |
| 0x39             | 0111001        | 27.5      |         |           |

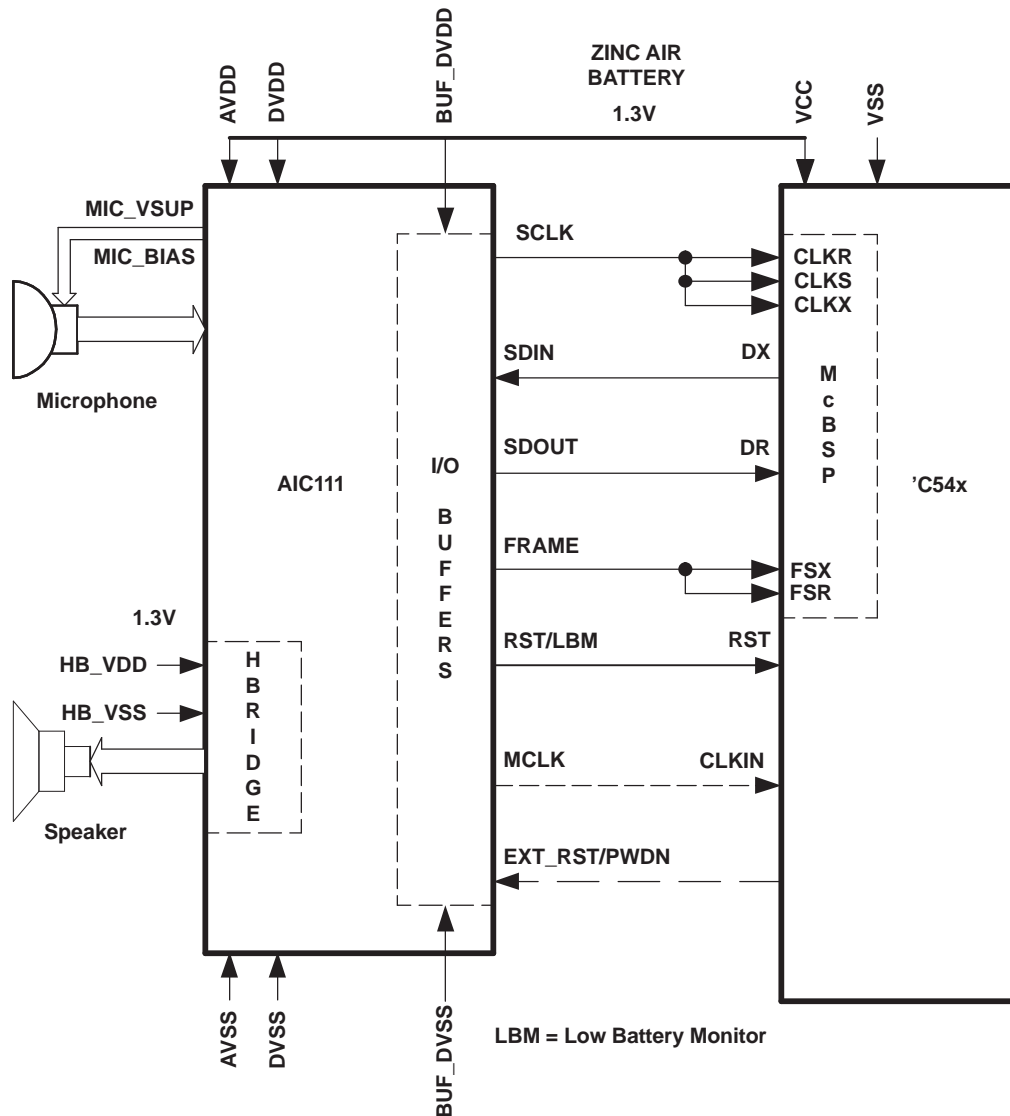
**Table 15. PGAC GAIN (continued)**

| PGAC GAIN VALUES |                |           |         |           |
|------------------|----------------|-----------|---------|-----------|
|                  | BUS NAME       | HEX VALUE | BINARY  | GAIN (dB) |
| PGAC             | PGAC_GAIN<6:0> | 0x38      | 0111000 | 27        |
|                  |                | 0x37      | 0110111 | 26.5      |
|                  |                | 0x36      | 0110110 | 26        |
|                  |                | 0x35      | 0110101 | 25.5      |
|                  |                | 0x34      | 0110100 | 25        |
|                  |                | 0x33      | 0110011 | 24.5      |
|                  |                | 0x32      | 0110010 | 24        |
|                  |                | 0x31      | 0110001 | 23.5      |
|                  |                | 0x30      | 0110000 | 23        |
|                  |                | 0x2F      | 0101111 | 22.5      |
|                  |                | 0x2E      | 0101110 | 22        |
|                  |                | 0x2D      | 0101101 | 21.5      |
|                  |                | 0x2C      | 0101100 | 21        |
|                  |                | 0x2B      | 0101011 | 20.5      |
|                  |                | 0x2A      | 0101010 | 20        |
|                  |                | 0x29      | 0101001 | 19.5      |
|                  |                | 0x28      | 0101000 | 19        |
|                  |                | 0x27      | 0100111 | 18.5      |
|                  |                | 0x26      | 0100110 | 18        |
|                  |                | 0x25      | 0100101 | 17.5      |
| 0x24             | 0100100        | 17        |         |           |
| 0x23             | 0100011        | 16.5      |         |           |

**Table 15. PGAC GAIN (continued)**

| PGAC GAIN VALUES |                |           |         |           |
|------------------|----------------|-----------|---------|-----------|
|                  | BUS NAME       | HEX VALUE | BINARY  | GAIN (dB) |
| PGAC (Continued) | PGAC_GAIN<6:0> | 0x22      | 0100010 | 16        |
|                  |                | 0x21      | 0100001 | 15.5      |
|                  |                | 0x20      | 0100000 | 15        |
|                  |                | 0x1F      | 0011111 | 14.5      |
|                  |                | 0x1E      | 0011110 | 14        |
|                  |                | 0x1D      | 0011101 | 13.5      |
|                  |                | 0x1C      | 0011100 | 13        |
|                  |                | 0x1B      | 0011011 | 12.5      |
|                  |                | 0x1A      | 0011010 | 12        |
|                  |                | 0x19      | 0011001 | 11.5      |
|                  |                | 0x18      | 0011000 | 11        |
|                  |                | 0x17      | 0010111 | 10.5      |
|                  |                | 0x16      | 0010110 | 10        |
|                  |                | 0x15      | 0010101 | 9.5       |
|                  |                | 0x14      | 0010100 | 9         |
|                  |                | 0x13      | 0010011 | 8.5       |
|                  |                | 0x12      | 0010010 | 8         |
|                  |                | 0x11      | 0010001 | 7.5       |
|                  |                | 0x10      | 0010000 | 7         |
|                  |                | 0x0F      | 0001111 | 6.5       |
|                  |                | 0x0E      | 0001110 | 6         |
|                  |                | 0x0D      | 0001101 | 5.5       |
|                  |                | 0x0C      | 0001100 | 5         |
|                  |                | 0x0B      | 0001011 | 4.5       |
| 0x0A             | 0001010        | 4         |         |           |
| 0x09             | 0001001        | 3.5       |         |           |
| 0x08             | 0001000        | 3         |         |           |
| 0x07             | 0000111        | 2.5       |         |           |
| 0x06             | 0000110        | 2         |         |           |
| PGAC             | PGAC_GAIN<6:0> | 0x05      | 0000101 | 1.5       |
|                  |                | 0x04      | 0000100 | 1         |
|                  |                | 0x03      | 0000011 | 0.5       |
|                  |                | 0x02      | 0000010 | 0         |
|                  |                | 0x01      | 0000001 | -0.5      |
|                  | Default        | 0x00      | 0000000 | -1        |

## TI TMS320C54xx APPLICATION CIRCUIT



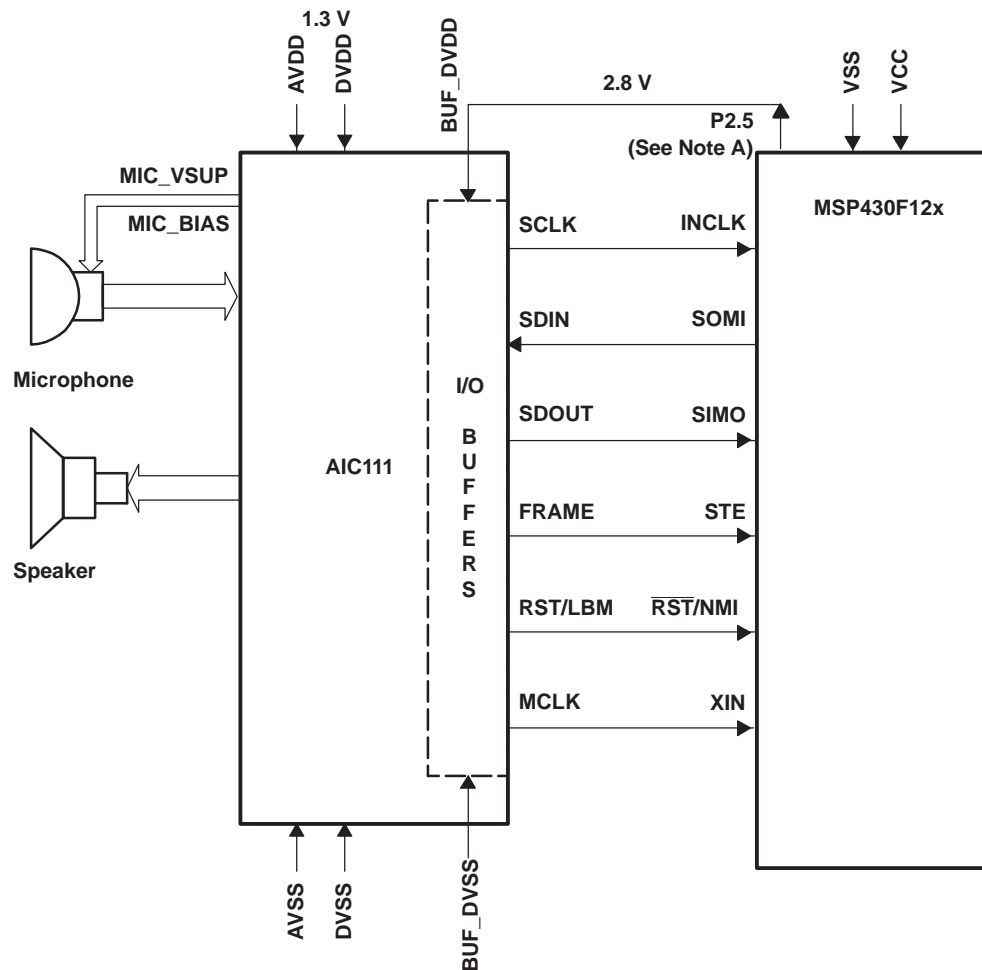
**Figure 13. Interfacing to the TMS320C54xx for a Hearing Aid Application**

Required external capacitors:

- 1- $\mu$ F coupling capacitor on AVINP, AVINM
- 1- $\mu$ F from VMID\_FILT to analog ground
- 1- $\mu$ F from VREF to analog ground
- 0.1- $\mu$ F from MIC\_VSUP to analog ground
- At least 0.1- $\mu$ F from VRFILT to analog ground. 1- $\mu$ F from VRFILT to analog ground is recommended.



TI MSP430F12x APPLICATION CIRCUIT



LBM = Low Battery Monitor '430 Can Also Use  
EXT\_RST/PWDN to Reset or Power Down the AIC111

Note A: P2.5 enables the MSP430F12x to shut down the AIC111 when desired.

Figure 14. Interfacing to the MSP430F12x for a Hearing Aid Application

MECHANICAL AND ENVIRONMENTAL

PACKAGING

The AIC111 is available in a 32-pin quad QFN 5x5-mm package. The AIC111 will be available 3rd quarter 2003 as bare solder ball bumped die intended for direct PCB mounting (also known as wafer scale packaging).

- For QFN packaged part in tubes order: AIC111RHB.
- For QFN packaged part in tape and reel order: AIC111RHBR.
- For ball bumped die (in waffle pack) order: AIC111YE (Preview, available 3rd quarter 2003).
- For ball bumped die (in tape and reel) order: AIC111YER (Preview, available 3rd quarter 2003).

**Table 16. BOND PAD PITCH AND DIE AREA**

| Die dimensions  |         | X = 2737.62 $\mu$ , Y = 3175.02 $\mu$ ,<br>(107.78 mil, 125.0 mil)<br>(2,74 mm, 3,18 mm) |          |                     |          |
|---|---------|--|----------|---------------------|----------|
| Maximum die area (includes scribe area)                                 |         | 13.47k $\mu$ m <sup>2</sup> (8.69mm <sup>2</sup> )                                       |          |                     |          |
| Minimum bond pad pitch  |         | 202.95 $\mu$ or 7.99 mil   |          |                     |          |
| Nearest   |         | PITCH  |          |                     |          |
| PAD (#)   | PAD (#) | (micron)   | (mil)    |                     |          |
| 7   | 8       | 202.950  | (7.990)  |                     |          |
| 30  | 31      | 202.950  | (7.990)  |                     |          |
| 12  | 13      | 237.690  | (9.358)  |                     |          |
| 14  | 15      | 237.690  | (9.358)  |                     |          |
| 16  | 15      | 237.690  | (9.358)  |                     |          |
| 28  | 29      | 241.200  | (9.496)  |                     |          |
| 18  | 19      | 256.410  | (10.095) |                     |          |
| 20  | 19      | 256.410  | (10.095) |                     |          |
| 21  | 20      | 256.410  | (10.095) |                     |          |
| 22  | 21      | 256.410  | (10.095) |                     |          |
| 25  | 26      | 287.651  | (11.325) |                     |          |
| 9   | 10      | 295.470  | (11.633) |                     |          |
| 10  | 11      | 295.470  | (11.633) |                     |          |
| 23  | 24      | 306.360  | (12.061) |                     |          |
| 1   | 32      | 327.147  | (12.880) |                     |          |
| 32  | 1       | 327.147  | (12.880) |                     |          |
| 4   | 5       | 356.940  | (14.053) |                     |          |
| 27  | 28      | 357.034  | (14.056) |                     |          |
| 17  | 16      | 359.453  | (14.152) |                     |          |
| 6   | 7       | 369.450  | (14.545) |                     |          |
| 2   | 1       | 371.520  | (14.627) |                     |          |
| 3   | 2       | 380.700  | (14.988) |                     |          |
| Number of pins  |         | 32   |          |                     |          |
| Pad locations:  |         | Bond Pad Coordinates   |          | Bond Pad Dimensions |          |
| Units: microns  |         | Pad #  | Xcenter  | Ycenter             | Diameter |
| Dimensions: X = 2737.62 Y = 3175  |         | 1  | 154.080  | 2808.990            | 70.020   |
| Bond pad origin: X = 0.000 Y = 0.000                                    |         | 2  | 154.080  | 2437.470            | 70.020   |
| Bond pad offset: X = 0.000 Y = 0.000                                    |         | 3  | 154.080  | 2056.770            | 70.020   |
| (X,Y) = (0,0) is located at the left bottom of the die by pads 8 and 9. |         | 4  | 154.080  | 1676.070            | 70.020   |
| See <a href="#">Figure 1</a> .  |         | 5  | 154.080  | 1319.130            | 70.020   |
|   |         | 6  | 154.080  | 938.430             | 70.020   |
|   |         | 7  | 154.080  | 568.980             | 70.020   |
|   |         | 8  | 154.080  | 366.030             | 70.020   |
|   |         | 9  | 410.310  | 162.630             | 70.020   |
|   |         | 10   | 705.780  | 162.630             | 70.020   |
|   |         | 11   | 1001.250 | 162.630             | 70.020   |
|   |         | 12   | 1327.860 | 162.630             | 70.020   |
|   |         | 13   | 1565.550 | 162.630             | 70.020   |
|   |         | 14   | 1803.240 | 162.630             | 70.020   |
|   |         | 15   | 2040.930 | 162.630             | 70.020   |
|   |         | 16   | 2278.620 | 162.630             | 70.020   |
|   |         | 17   | 2574.990 | 366.030             | 70.020   |

**Table 16. BOND PAD PITCH AND DIE AREA (continued)**

| Die dimensions | X = 2737.62 $\mu$ , Y = 3175.02 $\mu$ ,<br>(107.78 mil, 125.0 mil)<br>(2,74 mm, 3,18 mm) |          |          |         |
|----------------|--|----------|----------|---------|
|                |  | 18       | 2574.990 | 782.550 |
|                | 19   | 2574.990 | 1038.960 | 70.020  |
|                | 20   | 2574.990 | 1295.370 | 70.020  |
|                | 21   | 2574.990 | 1551.780 | 70.020  |
|                | 22   | 2574.990 | 1808.190 | 70.020  |
|                | 23   | 2574.990 | 2188.890 | 70.020  |
|                | 24   | 2574.990 | 2495.250 | 70.020  |
|                | 25   | 2574.990 | 2808.990 | 70.020  |
|                | 25   | 2371.590 | 3012.390 | 70.020  |
|                | 27   | 1910.430 | 2994.390 | 70.020  |
|                | 28   | 1553.850 | 3012.390 | 70.020  |
|                | 29   | 1312.650 | 3012.390 | 70.020  |
|                | 30   | 955.530  | 3012.390 | 70.020  |
|                | 31   | 752.580  | 3012.390 | 70.020  |
|                | 32   | 410.310  | 3012.390 | 70.020  |

**Table 17. DIE THICKNESS**

|   | TYPICAL                  | TOLERANCE                    |
|---|--------------------------|------------------------------|
| Final die thickness Z (without solder bump) | 29.59 mil or 725 $\mu$ m | $\pm$ 0.79 mil or 20 $\mu$ m |

**SOLDER BUMP**

- Bump metal composition: 37% Pb (lead)/63% Sn (tin)
- Type: Spherical

| BUMP SPEC.          | TYPICAL     | TOLERANCE   | NOTE                           |
|---------------------|-------------|-------------|--------------------------------|
| Bump height         | 100 $\mu$ m | +8 $\mu$ m  | Tolerance across a single die. |
|                     |             | +16 $\mu$ m | Tolerance across any wafer.    |
| Re-flow temperature | 183°C       |             |                                |

**WAFFLE SCALE PACKAGE DISCLAIMERS FOR AIC111YE AND AIC111YER**

- The AIC111's die bond pads, their peripheral placement, passivation opening, and layout are in accordance with ASE's *Bumping Design Guide* revision D, June, 2001.
- The final application is assumed to use plastic overmolding where the die is hermetically sealed, and the maximum ratings apply only to the QFN package and not to the WSCP.

**PACKAGING INFORMATION**

| Orderable Device | Status<br>(1) | Package Type | Package Drawing | Pins | Package Qty | Eco Plan<br>(2)         | Lead/Ball Finish | MSL Peak Temp<br>(3) | Op Temp (°C) | Top-Side Markings<br>(4) | Samples                 |
|------------------|---------------|--------------|-----------------|------|-------------|-------------------------|------------------|----------------------|--------------|--------------------------|-------------------------|
| AIC111RHB        | ACTIVE        | QFN          | RHB             | 32   | 73          | Green (RoHS & no Sb/Br) | Call TI          | Level-2-260C-1 YEAR  | 0 to 70      | AIC111                   | <a href="#">Samples</a> |
| AIC111RHBG4      | ACTIVE        | QFN          | RHB             | 32   | 73          | Green (RoHS & no Sb/Br) | Call TI          | Level-2-260C-1 YEAR  | 0 to 70      | AIC111                   | <a href="#">Samples</a> |
| AIC111YE         | ACTIVE        | DIESALE      | YE              | 32   | 49          | Green (RoHS & no Sb/Br) | Call TI          | Level-1-260C-UNLIM   | 0 to 70      | AIC111YE                 | <a href="#">Samples</a> |

(1) The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

**LIFEBUY:** TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.

**OBsolete:** TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

**TBD:** The Pb-Free/Green conversion plan has not been defined.

**Pb-Free (RoHS):** TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

**Pb-Free (RoHS Exempt):** This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

**Green (RoHS & no Sb/Br):** TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) Multiple Top-Side Markings will be inside parentheses. Only one Top-Side Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Top-Side Marking for that device.

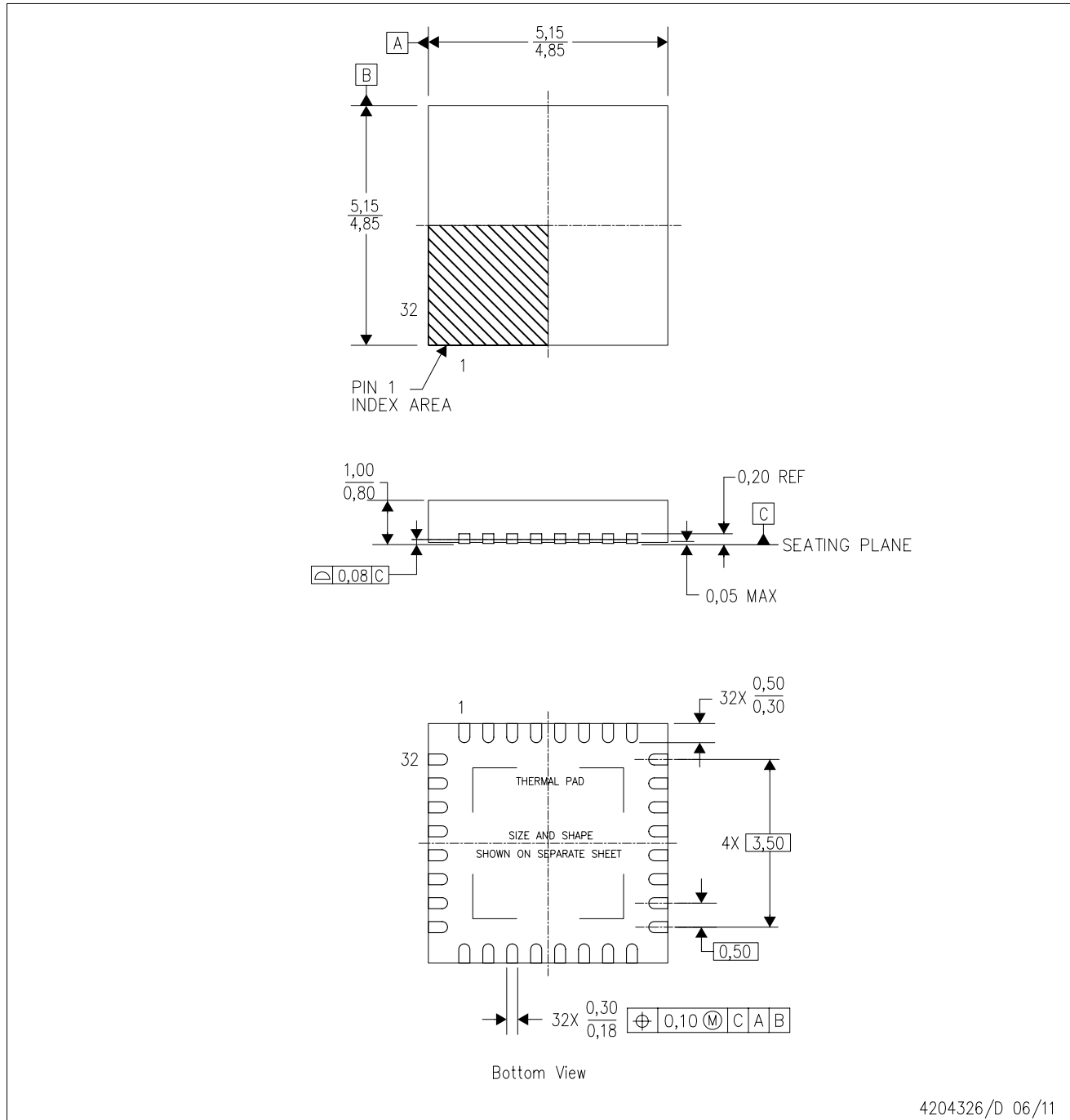
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# MECHANICAL DATA

RHB (S-PVQFN-N32)

PLASTIC QUAD FLATPACK NO-LEAD



4204326/D 06/11

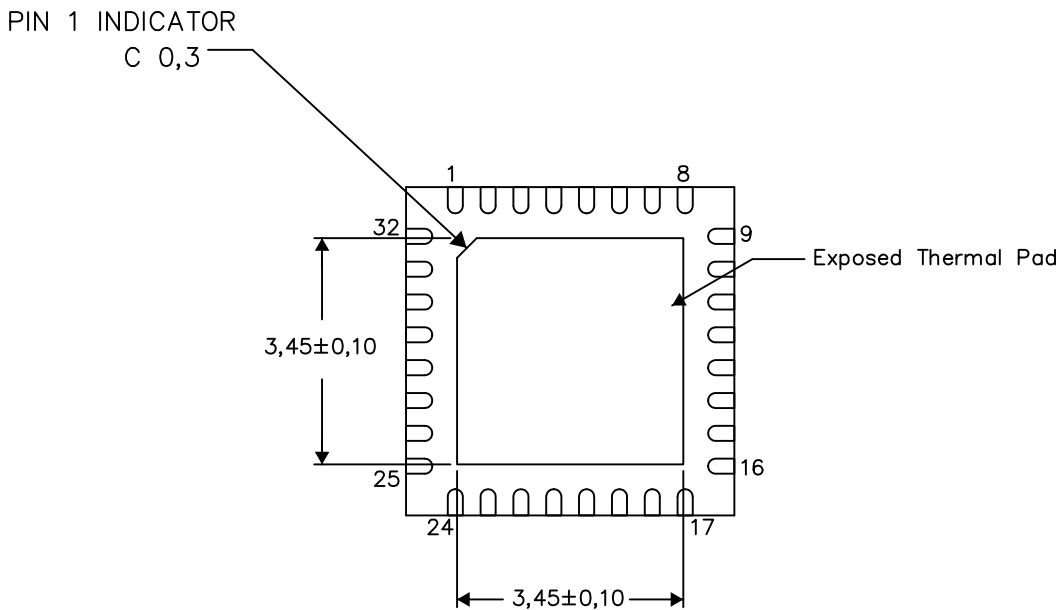
- NOTES:
- All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M-1994.
  - This drawing is subject to change without notice.
  - QFN (Quad Flatpack No-Lead) Package configuration.
  - The package thermal pad must be soldered to the board for thermal and mechanical performance.
  - See the additional figure in the Product Data Sheet for details regarding the exposed thermal pad features and dimensions.
  - Falls within JEDEC MO-220.

THERMAL INFORMATION

This package incorporates an exposed thermal pad that is designed to be attached directly to an external heatsink. The thermal pad must be soldered directly to the printed circuit board (PCB). After soldering, the PCB can be used as a heatsink. In addition, through the use of thermal vias, the thermal pad can be attached directly to the appropriate copper plane shown in the electrical schematic for the device, or alternatively, can be attached to a special heatsink structure designed into the PCB. This design optimizes the heat transfer from the integrated circuit (IC).

For information on the Quad Flatpack No-Lead (QFN) package and its advantages, refer to Application Report, QFN/SON PCB Attachment, Texas Instruments Literature No. SLUA271. This document is available at [www.ti.com](http://www.ti.com).

The exposed thermal pad dimensions for this package are shown in the following illustration.



Bottom View

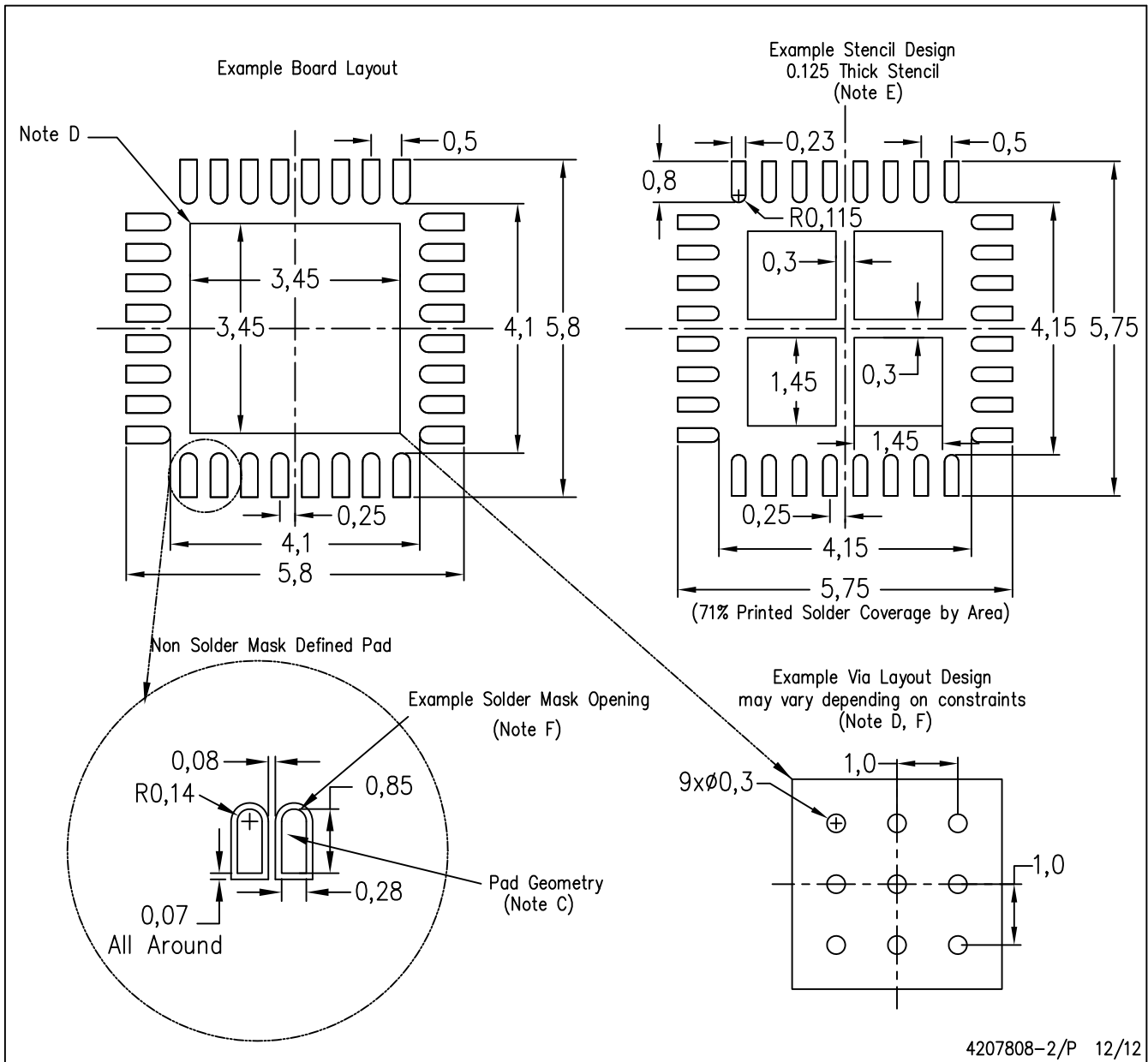
Exposed Thermal Pad Dimensions

4206356-2/X 12/12

NOTE: A. All linear dimensions are in millimeters

RHB (S-PVQFN-N32)

PLASTIC QUAD FLATPACK NO-LEAD



- NOTES:
- All linear dimensions are in millimeters.
  - This drawing is subject to change without notice.
  - Publication IPC-7351 is recommended for alternate designs.
  - This package is designed to be soldered to a thermal pad on the board. Refer to Application Note, Quad Flat-Pack Packages, Texas Instruments Literature No. SLUA271, and also the Product Data Sheets for specific thermal information, via requirements, and recommended board layout. These documents are available at [www.ti.com](http://www.ti.com) <<http://www.ti.com>>.
  - Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC 7525 for stencil design considerations.
  - Customers should contact their board fabrication site for recommended solder mask tolerances and via tenting recommendations for vias placed in the thermal pad.

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